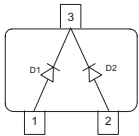


**Silicon Switching Diode**

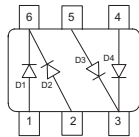
- For high-speed switching applications
- Common cathode configuration
- BAV70S / U: For orientation in reel see package information below
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101



**BAV70**  
**BAV70W**



**BAV70S**  
**BAV70U**



Type	Package	Configuration	Marking
BAV70	SOT23	common cathode	A4s
BAV70S	SOT363	double common cathode	A4s
BAV70U	SC74	double common cathode	A4s
BAV70W	SOT323	common cathode	A4s

<sup>1</sup>Pb-containing package may be available upon special request

**Maximum Ratings** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	$V_R$	80	V
Peak reverse voltage	$V_{RM}$	85	
Forward current	$I_F$	200	mA
Non-repetitive peak surge forward current	$I_{FSM}$		A
$t = 1 \mu\text{s}$		4.5	
$t = 1 \text{ ms}$		1	
$t = 1 \text{ s single}$		0.5	
$t = 1 \text{ s double}$		0.75	
Total power dissipation	$P_{tot}$		mW
BAV70, $T_S \leq 33^\circ\text{C}$		250	
BAV70S, $T_S \leq 85^\circ\text{C}$		250	
BAV70U, $T_S \leq 90^\circ\text{C}$		250	
BAV70W, $T_S \leq 103^\circ\text{C}$		250	
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-65 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	$R_{thJS}$		K/W
BAV70		$\leq 460$	
BAV70S		$\leq 260$	
BAV70U		$\leq 240$	
BAV70W		$\leq 190$	

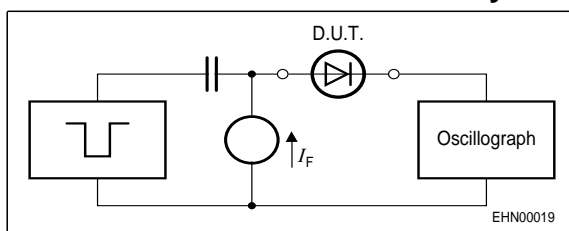
<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Breakdown voltage $I_{(BR)} = 100 \mu\text{A}$	$V_{(BR)}$	85	-	-	V
Reverse current $V_R = 70 \text{ V}$ $V_R = 25 \text{ V}, T_A = 150^\circ\text{C}$ $V_R = 70 \text{ V}, T_A = 150^\circ\text{C}$	$I_R$	-	-	0.15 30 50	$\mu\text{A}$
Forward voltage $I_F = 1 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 50 \text{ mA}$ $I_F = 100 \text{ mA}$ $I_F = 150 \text{ mA}$	$V_F$	-	-	715 855 1000 1200 1250	mV

**AC Characteristics**

Diode capacitance $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	$C_T$	-	-	1.5	pF
Reverse recovery time $I_F = 10 \text{ mA}, I_R = 10 \text{ mA}$ , measured at $I_R = 1 \text{ mA}$ , $R_L = 100 \Omega$	$t_{rr}$	-	-	4	ns

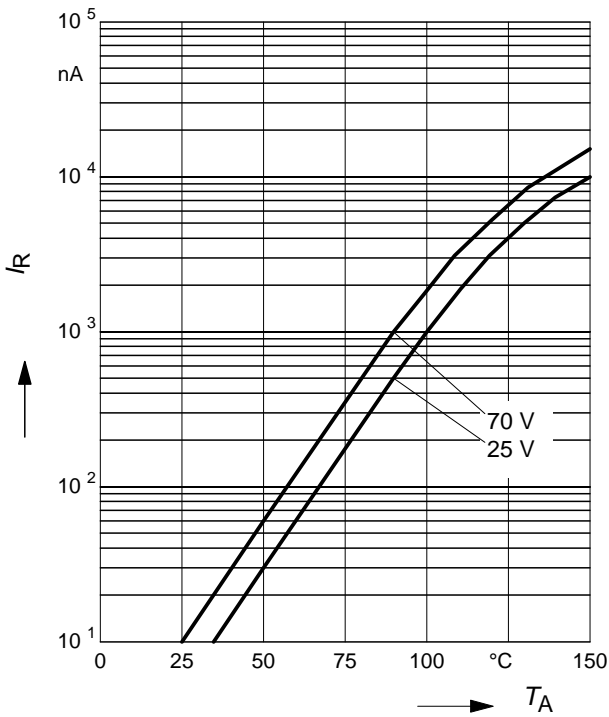
**Test circuit for reverse recovery time**


Pulse generator:  $t_p = 100\text{ns}$ ,  $D = 0.05$ ,  $t_r = 0.6\text{ns}$ ,  
 $R_i = 50\Omega$

Oscilloscope:  $R = 50\Omega$ ,  $t_r = 0.35\text{ns}$ ,  $C = 0.05\text{pF}$

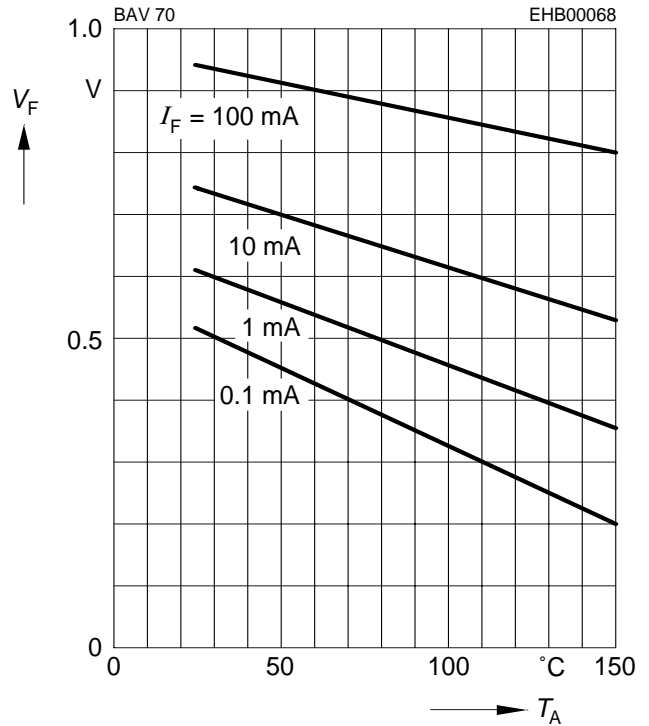
Reverse current  $I_R = f(T_A)$

$V_R =$  Parameter



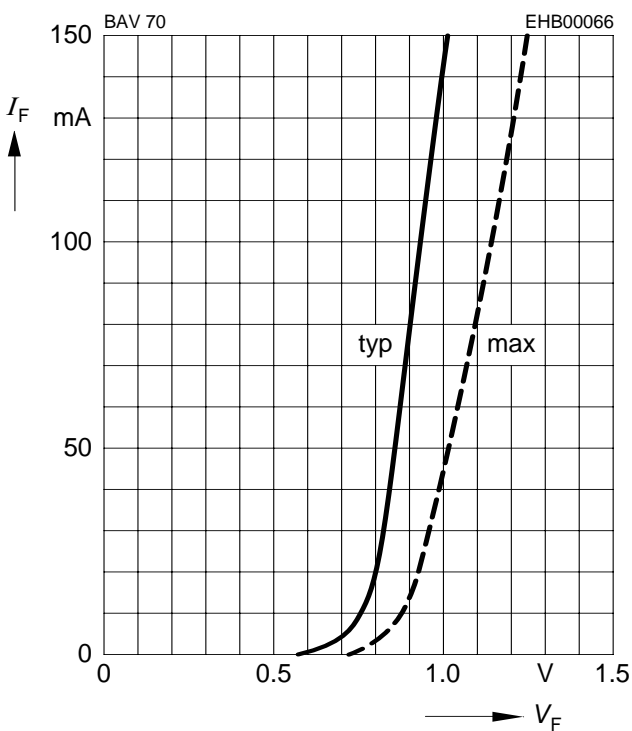
Forward Voltage  $V_F = f(T_A)$

$I_F =$  Parameter



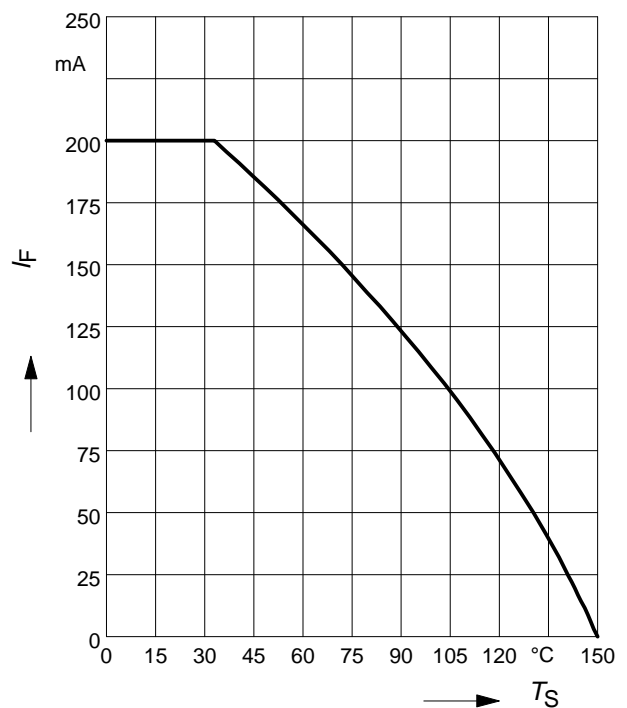
Forward current  $I_F = f(V_F)$

$T_A = 25^\circ\text{C}$



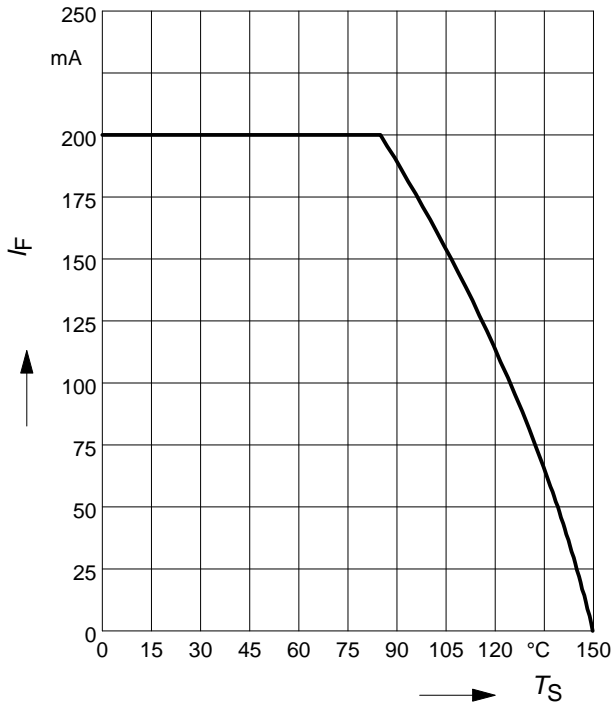
Forward current  $I_F = f(T_S)$

BAV70



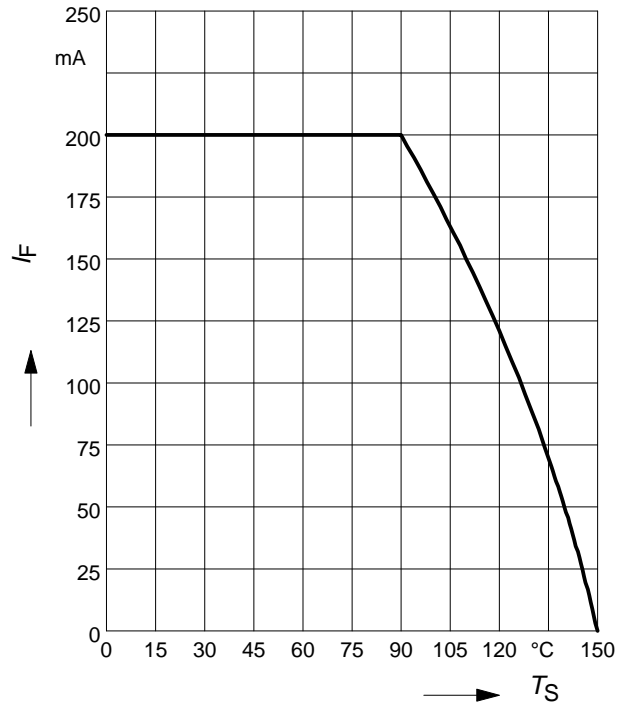
Forward current  $I_F = f(T_S)$

BAV70S



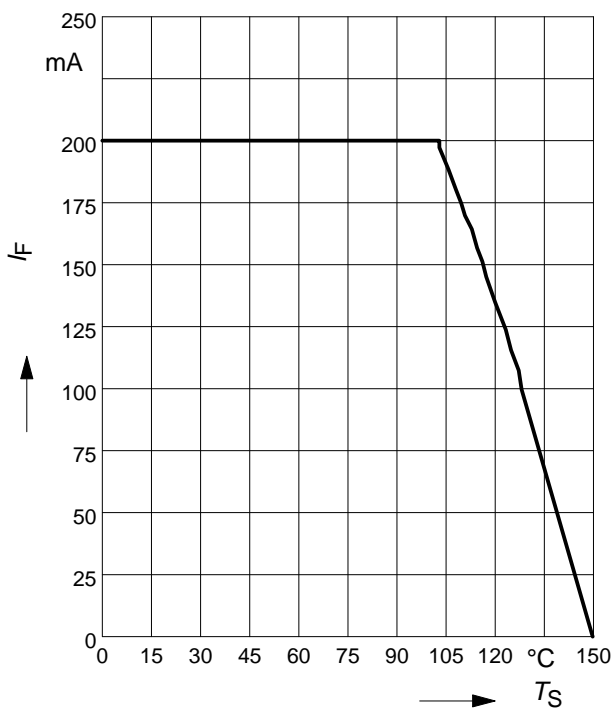
Forward current  $I_F = f(T_S)$

BAV70U



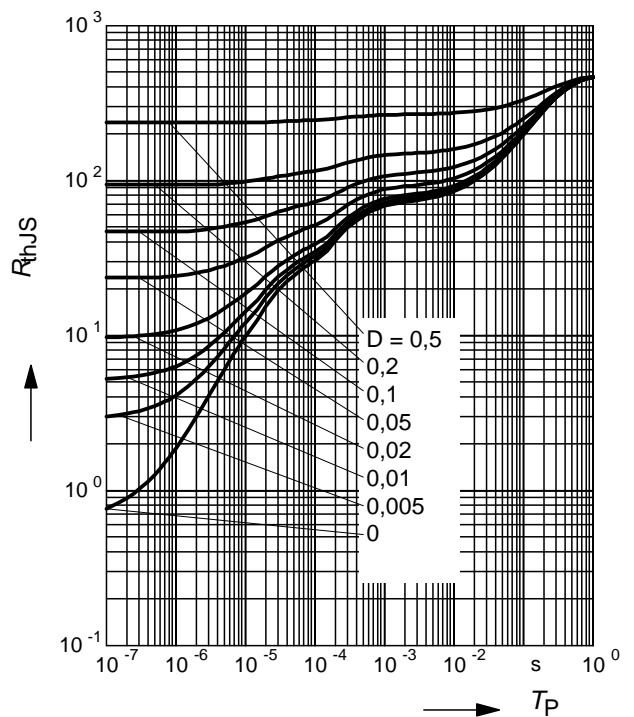
Forward current  $I_F = f(T_S)$

BAV70W



Permissible Puls Load  $R_{thJS} = f(t_p)$

BAV70



**Permissible Pulse Load**

$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAV70



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

BAV70S



**Permissible Pulse Load**

$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAV70S



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

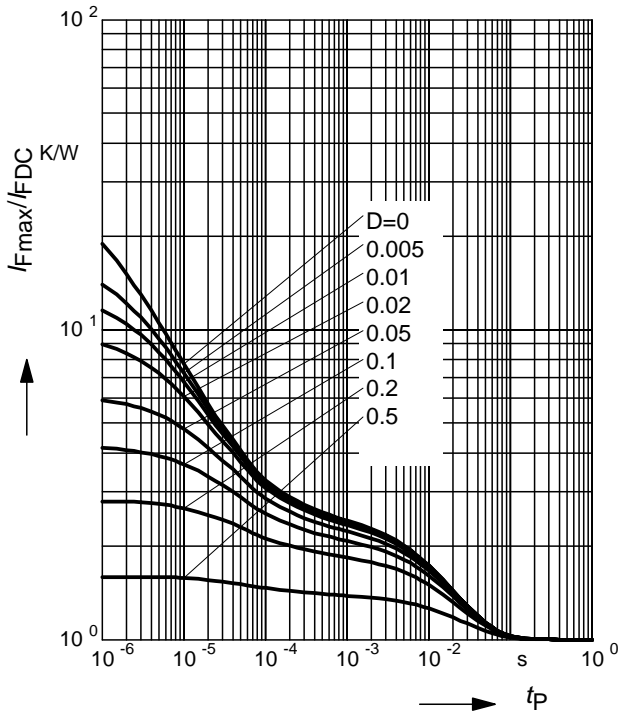
BAV70U



**Permissible Pulse Load**

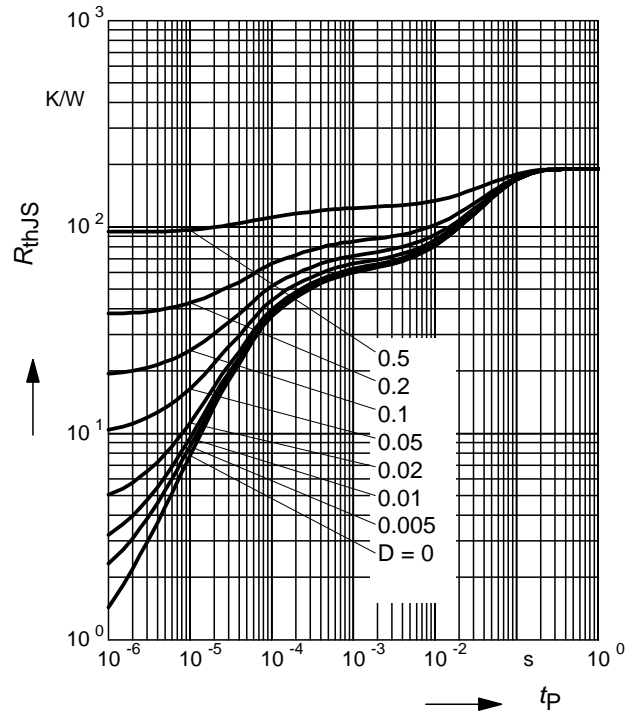
$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAV70U



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

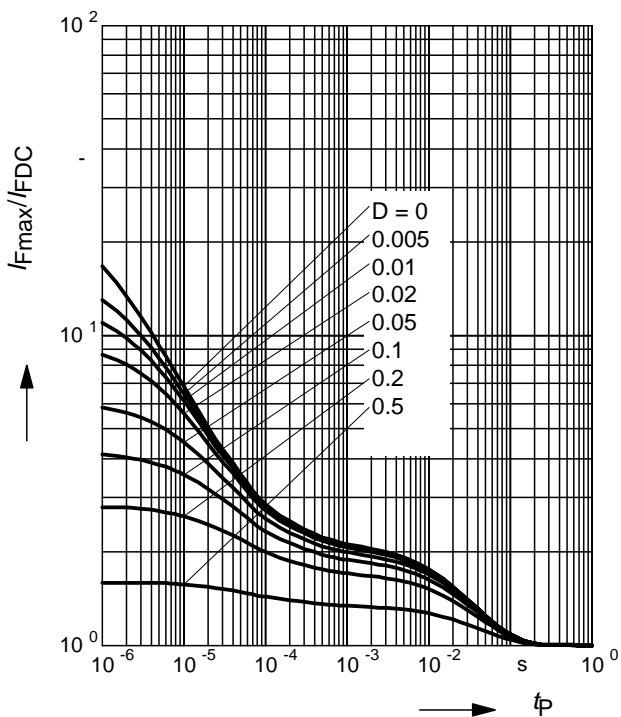
BAV70W



**Permissible Pulse Load**

$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAV70W



Package Outline



Foot Print



Marking Layout (Example)

Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.





Package Outline



1) Lead width can be 0.6 max. in dambar area

Foot Print



Marking Layout (Example)



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



Package Outline



Foot Print

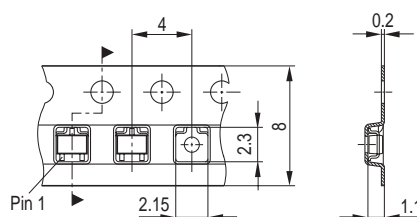


Marking Layout (Example)

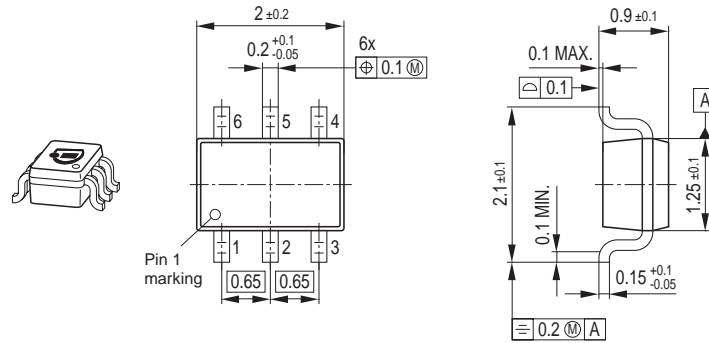


Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



Package Outline



Foot Print



Marking Layout (Example)

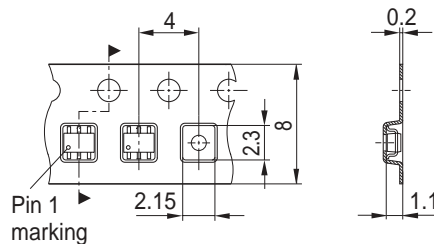
Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



Edition 2006-02-01  
Published by  
Infineon Technologies AG  
81726 München, Germany  
© Infineon Technologies AG 2007.  
All Rights Reserved.

### **Attention please!**

The information given in this dokument shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenhheitsgarantie"). With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

### **Information**

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office ([www.infineon.com](http://www.infineon.com)).

### **Warnings**

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system.

Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.